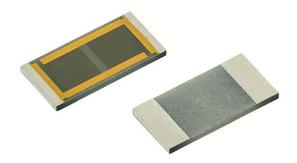


# High Power Aluminum Nitride, Wraparound Surface Mount, Precision Thin Film Chip Resistor (Up to 6 W)



# **LINKS TO ADDITIONAL RESOURCES**





PCAN series chip resistors are designed on aluminum nitride ceramic substrates with enlarged backside terminations to reduce the thermal resistance between the topside resistor layer and the solder joint on the end users circuit assembly.

Actual power handling capability is limited by the end user mounting process. As with any high power chip resistor the ability to remove the heat is critical to the overall performance of the device.

## **FEATURES**

High thermal conductivity aluminum nitride substrate



HALOGEN

**GREEN** 

(5-2008)

- Power rating up to 6.0 W
- Resistance range 2  $\Omega$  to 30.1 k $\Omega$
- Resistor tolerance to ± 0.1 %
- TCR to ± 25 ppm/°C
- Flame resistant UL 94 V-0
- Material categorization: for definitions of compliance please see <a href="https://www.vishay.com/doc?99912">www.vishay.com/doc?99912</a>

#### Note

\* This datasheet provides information about parts that are RoHS-compliant and / or parts that are non RoHS-compliant. For example, parts with lead (Pb) terminations are not RoHS-compliant. Please see the information / tables in this datasheet for details

# **APPLICATIONS**

- · Power supplies
- Power switching
- Braking system

# TYPICAL PERFORMANCE

	ABSOLUTE
TCR	25
TOL.	0.1

STANDARD ELECTRICAL SPECIFICATIONS			
TEST	SPECIFICATIONS	CONDITIONS	
Material	Passivated nichrome	=	
Resistance Range	2 Ω to 30.1 kΩ	-	
TCR: Absolute	25 ppm/°C (standard) and 100 ppm/°C	=	
Tolerance: Absolute	0.1 %, 0.25 %, 0.5 %, 1.0 %, 2.0 %, and 5.0 %	-55 °C to +150 °C	
Power Rating: Resistor	0.5 W to 6.0 W <sup>(1)</sup>	Maximum at +70 °C	
Stability: Absolute	ΔR 1.0 %	1000 h at +70 °C	
Voltage Coefficient	< 0.1 ppm/V	=	
Working Voltage	75 V to 100 V	-	
Operating Temperature Range	-55 °C to +155 °C	=	
Storage Temperature Range	-55 °C to +155 °C	-	
Noise	< -30 dB	=	
Shelf Life Stability: Absolute	± 0.01 %	1 year at +25 °C	

## Note

(1) Dependant on component mounting by user

COMPONENT RATINGS			
CASE SIZE	POWER RATING (mW)	WORKING VOLTAGE (V)	RESISTANCE RANGE ( $\Omega$ )
0603	500 <sup>(1)</sup>	75	2 to 30.1K
0805	1000 (1)	100	2 to 30.1K
1206	2000 (1)	100	2 to 30.1K
2512	6000 <sup>(1)</sup>	100	2 to 30.1K

## Note

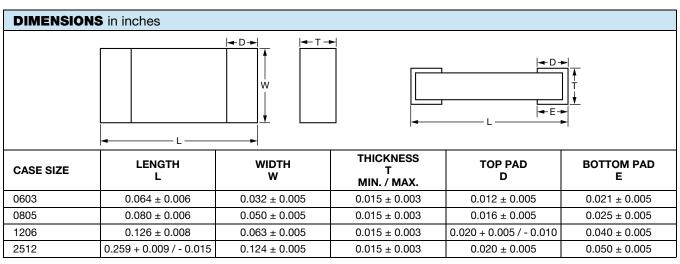
(1) Dependant on component mounting by user

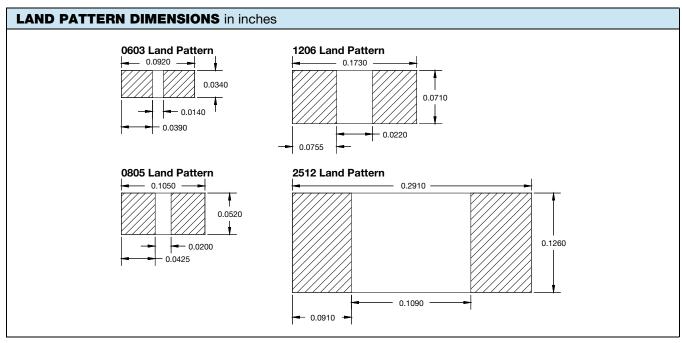


ENVIRONMENTAL TESTS		
ENVIRONMENTAL TEST (1)	TEST LIMITS	TYPICAL VISHAY PERFORMANCE
Resistance temperature characteristic	± 25 ppm/°C	± 15 ppm/°C
Maximum ambient temperature at rated wattage	+70 °C	+70 °C
Maximum ambient temperature at power derating	+150 °C	+150 °C
Thermal shock	± 0.25 %	± 0.10 %
Low temperature operation	± 0.25 %	± 0.01 %
Short time overload	± 0.5 %	± 0.2 %
High temperature exposure	± 0.2 %	± 0.05 %
Resistance to soldering heat	± 0.25 %	± 0.025 %
Moisture resistance	± 0.4 %	± 0.01 %
Life at +70 °C for 1000 h	± 1.00 %	± 0.4 %

#### Note

<sup>(1)</sup> Environmental testing was performed based on MIL-STD-202 standard test methods

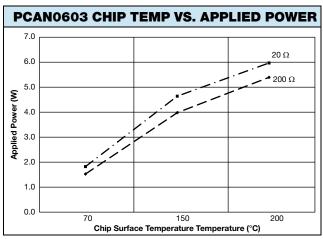




Revision: 08-Mar-2021 2 Document Number: 60125

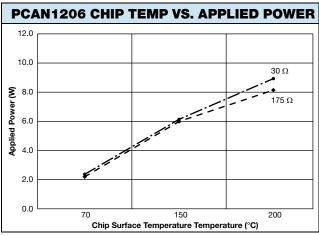


STANDARD MATERIAL SPECIFICATIONS		
Resistive element	Passivated nichrome	
Substrate material	Aluminum nitride	
Terminations (tin/lead)	Tin / lead solder over nickel barrier	
Terminations (lead (Pb)-free)	Tin / silver / copper (Sn96.5 / Ag3.0 / Cu0.5) solder over nickel barrier	



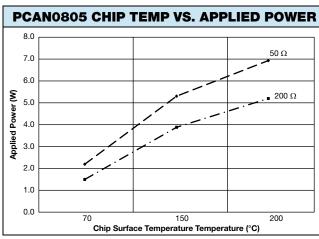
#### Note

 Chip surface temperature measured using FLIR SC645 thermal imaging system with an approximate testcard surface temperature of 75 °C



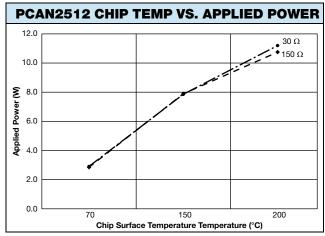
## Note

- Chip surface temperature measured using FLIR SC645 thermal imaging system with an approximate test card surface temperature of 85 °C
- Thermal imaging was conducted under ambient conditions resulting in a steady state test card surface temperature of 85 °C over the full range of power levels
- Thermal imaging and load life testing was conducted mounting one device to a 1.6" x 3.7" test card with 3.5 mil copper plating on both surfaces. Thermal vias on 50 mil centers were utilized for heat transfer between surfaces of the test card



## Note

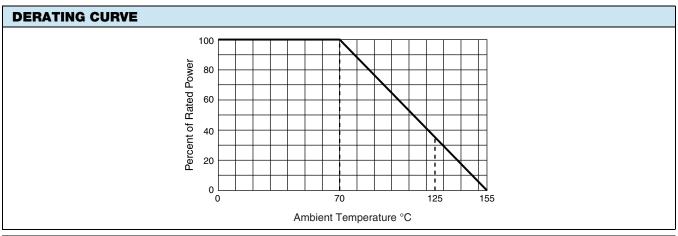
 Chip surface temperature measured using FLIR SC645 thermal imaging system with an approximate testcard surface temperature of 75 °C

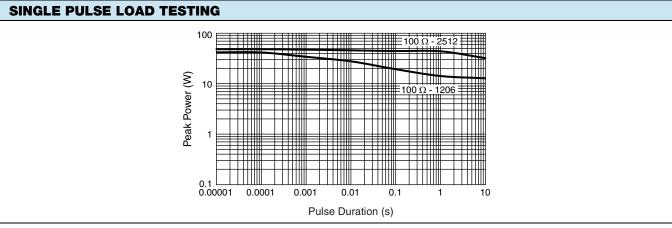


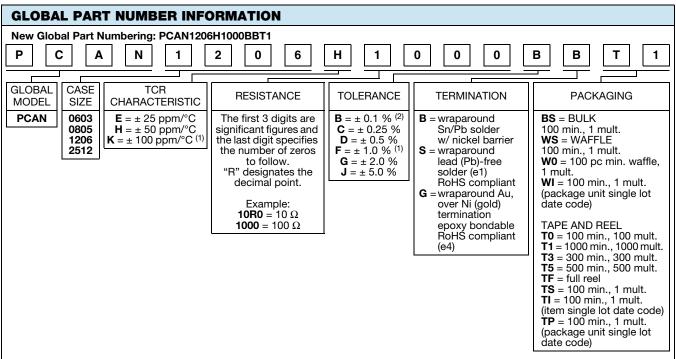
## Note

 Chip surface temperature measured using FLIR SC645 thermal imaging system with an approximate test card surface temperature of 85 °C









## Notes

 $^{(1)}$  Less than 10  $\Omega.$  100 ppm/°C and 1 % tolerance best

 $\ensuremath{^{(2)}}$  Available on 10  $\Omega$  and higher

# **Legal Disclaimer Notice**



Vishay

# **Disclaimer**

ALL PRODUCT, PRODUCT SPECIFICATIONS AND DATA ARE SUBJECT TO CHANGE WITHOUT NOTICE TO IMPROVE RELIABILITY, FUNCTION OR DESIGN OR OTHERWISE.

Vishay Intertechnology, Inc., its affiliates, agents, and employees, and all persons acting on its or their behalf (collectively, "Vishay"), disclaim any and all liability for any errors, inaccuracies or incompleteness contained in any datasheet or in any other disclosure relating to any product.

Vishay makes no warranty, representation or guarantee regarding the suitability of the products for any particular purpose or the continuing production of any product. To the maximum extent permitted by applicable law, Vishay disclaims (i) any and all liability arising out of the application or use of any product, (ii) any and all liability, including without limitation special, consequential or incidental damages, and (iii) any and all implied warranties, including warranties of fitness for particular purpose, non-infringement and merchantability.

Statements regarding the suitability of products for certain types of applications are based on Vishay's knowledge of typical requirements that are often placed on Vishay products in generic applications. Such statements are not binding statements about the suitability of products for a particular application. It is the customer's responsibility to validate that a particular product with the properties described in the product specification is suitable for use in a particular application. Parameters provided in datasheets and / or specifications may vary in different applications and performance may vary over time. All operating parameters, including typical parameters, must be validated for each customer application by the customer's technical experts. Product specifications do not expand or otherwise modify Vishay's terms and conditions of purchase, including but not limited to the warranty expressed therein.

Hyperlinks included in this datasheet may direct users to third-party websites. These links are provided as a convenience and for informational purposes only. Inclusion of these hyperlinks does not constitute an endorsement or an approval by Vishay of any of the products, services or opinions of the corporation, organization or individual associated with the third-party website. Vishay disclaims any and all liability and bears no responsibility for the accuracy, legality or content of the third-party website or for that of subsequent links.

Except as expressly indicated in writing, Vishay products are not designed for use in medical, life-saving, or life-sustaining applications or for any other application in which the failure of the Vishay product could result in personal injury or death. Customers using or selling Vishay products not expressly indicated for use in such applications do so at their own risk. Please contact authorized Vishay personnel to obtain written terms and conditions regarding products designed for such applications.

No license, express or implied, by estoppel or otherwise, to any intellectual property rights is granted by this document or by any conduct of Vishay. Product names and markings noted herein may be trademarks of their respective owners.